

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-source Voltage	BV_{DSX}
Source-to-drain Voltage.....	BV_{SDX}
Gate-to-source Voltage	-12V to +0.6V
Gate-to-drain Voltage	-12V to +0.6V
Operating Ambient Temperature, T_A	-25°C to +125°C

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. (**Note 1**)

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-source Breakdown Voltage	BV_{DSX}	9	—	—	V	$V_{GS} = -3\text{V}$, $I_{DS} = 10\text{ }\mu\text{A}$
Source-to-drain Breakdown Voltage	BV_{SDX}	9	—	—	V	$V_{GD} = -3\text{V}$, $I_{SD} = 10\text{ }\mu\text{A}$
Gate-to-source Off Voltage	$V_{GS(OFF)}$	-0.8	—	-3	V	$V_{DS} = 9\text{V}$, $I_{DS} = 1\text{ }\mu\text{A}$
Source-to-gate Off Voltage	$V_{SG(OFF)}$	-0.8	—	-3	V	$V_{SD} = 9\text{V}$, $I_{SD} = 1\text{ }\mu\text{A}$
Gate-to-source Diode	V_{GS}	-12	—	0.6	V	$I_{GS} = \pm 1\text{ }\mu\text{A}$
Gate-to-drain Diode	V_{GD}	-12	—	0.6	V	$I_{GD} = \pm 1\text{ }\mu\text{A}$
Drain-to-source Leakage Current	$I_{DS(OFF)}$	—	—	1	μA	$V_{GS} = -3\text{V}$, $V_{DS} = 9\text{V}$
Source-to-drain Leakage Current	$I_{SD(OFF)}$	—	—	1	μA	$V_{GD} = -3\text{V}$, $V_{SD} = 9\text{V}$
Saturated Drain-to-source Current	I_{DSS}	300	—	—	mA	$V_{GS} = 0\text{V}$, $V_{DS} = 9\text{V}$
Saturated Source-to-drain Current	I_{SDS}	300	—	—	mA	$V_{GD} = 0\text{V}$, $V_{SD} = 9\text{V}$
Static Drain-to-source On-state Resistance	$R_{DS(ON)}$	—	0.9	1.4	Ω	$V_{GS} = 0\text{V}$, $I_{DS} = 100\text{ mA}$
Static Source-to-drain On-state Resistance	$R_{SD(ON)}$	—	0.9	1.4	Ω	$V_{GD} = 0\text{V}$, $I_{SD} = 100\text{ mA}$

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated.
(Pulse test: 300 μs pulse, 2% duty cycle)

2: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. (**Note 2**)

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G_{FS}	200	—	—	mmho	$V_{DS} = 9\text{V}$, $I_{DS} = 50\text{ mA}$
Input Capacitance	C_{ISS}	—	46	—	pF	$V_{GS} = -3\text{V}$, $V_{DS} = 5\text{V}$, $f = 1\text{ MHz}$
Common Source Output Capacitance	C_{OSS}	—	32	—	pF	
Reverse Transfer Capacitance	C_{RSS}	—	23	—	pF	
Turn-on Delay Time	$t_{d(ON)}$	—	3.8	—	ns	$V_{DD} = 9\text{V}$, $I_{DS} = 100\text{ mA}$, $R_{GEN} = 25\Omega$
Rise Time	t_r	—	11	—	ns	
Turn-off Delay Time	$t_{d(OFF)}$	—	1	—	ns	
Fall Time	t_f	—	6.4	—	ns	

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated.
(Pulse test: 300 μs pulse, 2% duty cycle)

2: Specification is obtained by characterization and is not 100% tested.

TEMPERATURE SPECIFICATIONS

Electrical Characteristics: Unless otherwise specified, for all specifications $T_A = T_J = +25^\circ\text{C}$.						
Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-25	—	+125	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
5-lead SOT-23	θ_{JA}	—	253	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	$I_D^{(1)}$ (Continuous) (mA)	I_D (Pulsed) (mA)	Power Dissipation at $T_C = 25^\circ\text{C}$ (W)
5-lead SOT-23	330	600	0.36

Note 1: I_D (continuous) is limited by maximum T_J .

LND01

2.0 PIN DESCRIPTION

Table 2-1 shows the description of pins in LND01.
Refer to [Package Type](#) for the location of pins.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	N/C	Not connected
2	Gate	Gate
3	N/C	Not connected
4	Drain	Drain
5	Source	Source

3.0 FUNCTIONAL DESCRIPTION

Figure 3-1 illustrates the switching waveforms and test circuit for LND01.

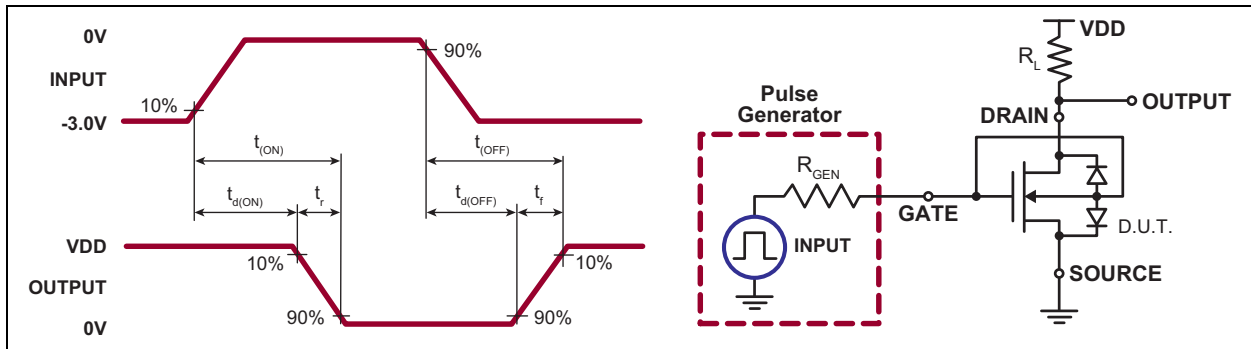


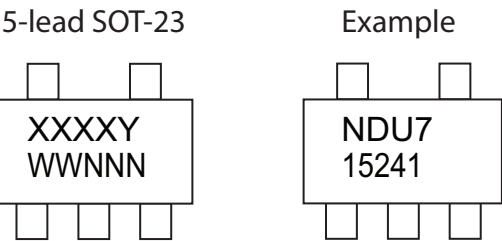
FIGURE 3-1: Switching Waveforms and Test Circuit.

TABLE 3-1: PRODUCT SUMMARY

BV_{DSX}/BV_{SDX} (V)	$R_{DS(ON)}/R_{SD(ON)}$ (Maximum) (Ω)	I_{DSS}/I_{SSD} (Maximum) (mA)
9	1.4	300

4.0 PACKAGING INFORMATION

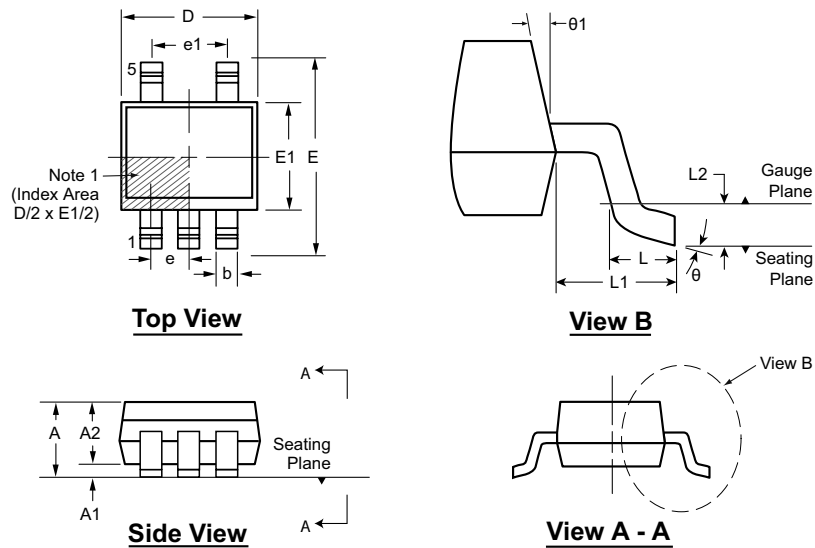
4.1 Package Marking Information



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
	(e4)	Pre-plated
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.	

5-Lead SOT-23 Package Outline (K1)

2.90x1.60mm body, 1.45mm height (max), 0.95mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol		A	A1	A2	b	D	E	E1	e	e1	L	L1	L2	θ	θ1
Dimension (mm)	MIN	0.90*	0.00	0.90	0.30	2.75*	2.60*	1.45*	0.95 BSC	1.90 BSC	0.30	0.60 REF	0.25 BSC	0°	5°
	NOM	-	-	1.15	-	2.90	2.80	1.60			0.45			4°	10°
	MAX	1.45	0.15	1.30	0.50	3.05*	3.00*	1.75*			0.60			8°	15°

JEDEC Registration MO-178, Variation AA, Issue C, Feb. 2000.

* This dimension is not specified in the JEDEC drawing.

Drawings not to scale.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (June 2017)

- Converted Supertex Doc# DSFP-LND01 to Microchip DS20005696A
- Changed the package marking format
- Changed the quantity of the 5-lead SOT-23 K1 package from 2500/Reel to 3000/Reel
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<div><div><div>PART NO.</div><div>Device</div></div><div><div>XX</div><div>Package Options</div></div><div>-</div><div><div>X</div><div>Environmental</div></div><div>-</div><div><div>X</div><div>Media Type</div></div></div>	<div>Example:</div> <div>a) LND01K1-G: Lateral N-Channel Depletion-Mode MOSFET, 5-lead SOT-23, 3000/Reel</div>
<div><div>Device: LND01 = Lateral N-Channel Depletion-Mode MOSFET</div><div>Package: K1 = 5-lead SOT-23</div><div>Environmental: G = Lead (Pb)-free/RoHS-compliant Package</div><div>Media Type: (blank) = 3000/Reel for a K1 Package</div></div>	

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